NOTES:

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.008
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICROINCHES (2.5um-7.6um) THICK.
   GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um-2um) THICK).
   BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220

PRESENTATION SPECIFICATIONS:

DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE:
ANGULAR: ±0.5 degree
.XX: ±0.05

REVISIONS

ZONE REV. DESCRIPTION DATE APPROVED
A ORIGINAL RELEASE 8/11/11 SS
B .045 PROFILE LIMIT WAS .05 5/16/2017 SS
C UPDATED DIMENSIONAL TOLERANCES 3/16/2022 SS

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